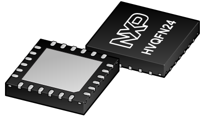

SOT1594-1

HVQFN24, plastic, thermal enhanced very thin quad flat package; no leads; 24 terminals; 0.65 mm pitch; 5 mm x 5 mm x 0.9 mm body

20 April 2020 Package information

1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	HVQFN24
Package type industry code	HVQFN24
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	12-01-2016
Manufacturer package code	98ASA00734D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	4.9	5	5.1	mm
package width	4.9	5	5.1	mm
package height	0.8	0.9	1	mm
nominal pitch	-	0.65	-	mm
actual quantity of termination	-	24	-	

2 Package outline

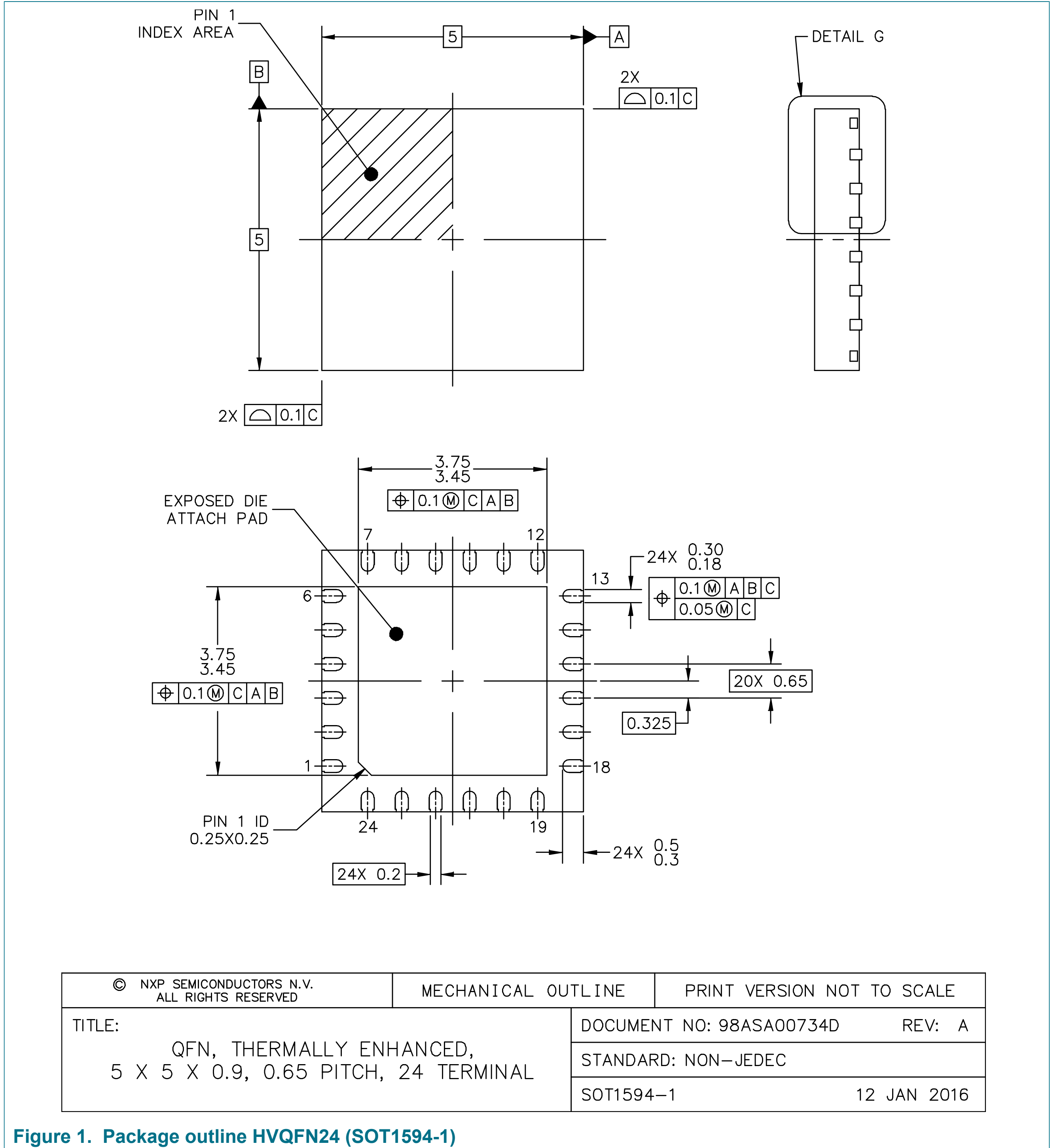

Figure 1. Package outline HVQFN24 (SOT1594-1)

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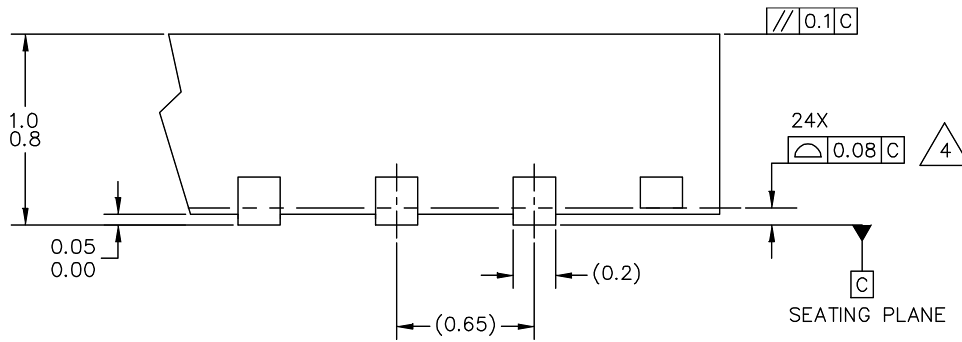

DETAIL G
VIEW ROTATED 90°CW

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TITLE: QFN, THERMALLY ENHANCED, 5 X 5 X 0.9, 0.65 PITCH, 24 TERMINAL	DOCUMENT NO: 98ASA00734D	REV: A
	STANDARD: NON–JEDEC	
	SOT1594–1	12 JAN 2016

Figure 2. Package outline detail HVQFN24 (SOT1594-1)

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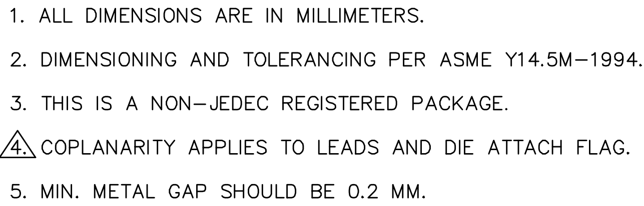

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TITLE: QFN, THERMALLY ENHANCED, 5 X 5 X 0.9, 0.65 PITCH, 24 TERMINAL	DOCUMENT NO: 98ASA00734D	REV: A
	STANDARD: NON-JEDEC	
	SOT1594-1	12 JAN 2016

Figure 3. Package outline note HVQFN24 (SOT1594-1)

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3 Legal information

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Contents

1 Package summary 1
2 Package outline 2
3 Legal information 5

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Date of release: 20 April 2020